



## Advances in Conducting and Semiconducting Materials

Guest Editor:

**Prof. Dr. Wen-Hsi Lee**

Department of Electrical  
Engineering, National Cheng  
Kung University, Tainan, Taiwan

Deadline for manuscript  
submissions:

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### Message from the Guest Editor

Dear Colleagues,

The scope of application of conductor and semiconductor materials is vast. These materials find utilities not only electrical modules, devices, etc., but are also used as components, circuits, and other auxiliaries related to electronics, computers, and instrumentation fields. Advanced conductors that outperform silver, copper, and nanocarbon can revolutionize the electronics industry. Advanced semiconductors that have such superior performance (e.g., high voltage resistance, high efficiency, high radiation resistance) are the "core" of a new generation of information technology, prioritizing energy saving and smart manufacturing. Understanding film materials, process control, kinetics, growth, microstructure, and electrical properties are important for microelectronic applications of advanced conductor and semiconductor materials.

We invite colleagues to contribute to this Special Issue on the aforementioned concepts and keywords. The goal for this Special Issue is to describe the recent developments in this rapidly developing interdisciplinary research field. Full papers, communications, and reviews are all welcome.

Prof. Dr. Wen-Hsi Lee

*Guest Editor*





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### Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

## Message from the Editor-in-Chief

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*Materials* Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

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